

In the Specification:

Under the heading "Brief Description of the Drawings" on page 5, beginning at line 19, please revise that paragraph to read as follows:

~~--FIG. 2 is a schematic~~ FIGs. 2a – 2c (collectively FIG. 2) are schematics of the non-destructive method of measuring recess depth of a wafer utilizing a solvent in accordance with the invention process.--